

Title (en)

PHOTOLYTIC CONVERSION PROCESS TO FORM PATTERNED AMORPHOUS FILM

Title (de)

PHOTOLYTISCHES KONVERSIONSVERFAHREN ZUR HERSTELLUNG STRUKTURIERTER AMORPHER FILME

Title (fr)

PROCEDE DE CONVERSION CATALYTIQUE POUR FORMATION DE FILM AMORPHE A MOTIFS

Publication

EP 1434899 A2 20040707 (EN)

Application

EP 02784016 A 20021004

Priority

- US 0231683 W 20021004
- US 32700901 P 20011005

Abstract (en)

[origin: WO03031682A2] The invention is directed to a photoresist-free method for depositing films composed of metals, such as copper or silica, or their oxides from metal complexes. More specifically, the method involves applying an amorphous film of a metal complex to a substrate. The metal complexes have a metal and a photo-degradable ligand. A preferred ligand is acac or alkyl-acac, especially in combination with acetate ligands. These films, upon, for example, thermal, photochemical or electron beam irradiation may be converted to the metal or its oxides. By using either directed light or electron beams, this may lead to a patterned metal or metal oxide film in a single step. Low temperature baking may be used to remove residual organics from the deposited film. If silica is the metal, the deposited film has excellent smoothness and dielectric properties.

IPC 1-7

C23C 18/14; **C23C 18/12**; **C23C 18/06**

IPC 8 full level

C23C 20/06 (2006.01); **C23C 18/06** (2006.01); **C23C 18/12** (2006.01); **C23C 18/14** (2006.01)

CPC (source: EP KR US)

C23C 18/06 (2013.01 - EP KR US); **C23C 18/08** (2013.01 - EP KR); **C23C 18/1216** (2013.01 - EP KR); **C23C 18/1279** (2013.01 - EP KR); **C23C 18/1283** (2013.01 - EP KR); **C23C 18/143** (2019.04 - EP KR US); **C23C 18/14** (2013.01 - EP US); **C23C 18/145** (2019.04 - EP US)

Citation (search report)

See references of WO 03031682A2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR IE IT LI LU MC NL PT SE SK TR

DOCDB simple family (publication)

WO 03031682 A2 20030417; **WO 03031682 A3 20030828**; AU 2002347803 A1 20030422; CN 1608143 A 20050420; EP 1434899 A2 20040707; JP 2005505691 A 20050224; KR 20050033523 A 20050412; TW 593742 B 20040621

DOCDB simple family (application)

US 0231683 W 20021004; AU 2002347803 A 20021004; CN 02824255 A 20021004; EP 02784016 A 20021004; JP 2003534649 A 20021004; KR 20047005071 A 20040406; TW 91123118 A 20021007